



BC846BLP4

65V NPN SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

- Low Collector-Emitter Saturation Voltage, V_{CE(SAT)}
- Ultra-Small Leadless Surface Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Note 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu, Solderable per MIL-STD-202, Method 208 @
- Weight: 0.0009 grams (Approximate)

X2-DFN1006-3



Bottom View



Device Symbol



Top View Device Schematic

Ordering Information (Note 4)

Part Number	Marking	Reel Size (in)	Tape Width (mm)	Quantity per Reel
BC846BLP4-7B	3S	7	8	10,000
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.				

No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



3S = Product Type Marking Code

Top View Bar Denotes Base and Emitter Side



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	80	V
Collector-Emitter Voltage	V _{CEO}	65	V
Emitter-Base Voltage	V _{EBO}	6	V
Collector Current - Continuous	Ic	100	mA
Peak Collector Current	I _{CM}	200	mA
Peak Emitter Current	I _{EM}	200	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit		
Power Dissipation	(Note 5)	P	0.46	W	
	(Note 6)	- P _D	1		
Thermal Resistance, Junction to Ambient	(Note 5)	В	272	°C/W	
	(Note 6)	− R _{θJA}	120	C/ W	
Thermal Resistance, Junction to Leads (Note 7)		$R_{ extsf{ heta}JL}$	110	°C/W	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C		

ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	200	V	В

Notes: 5. For a device surface mounted on minimum recommended pad layout FR-4 PCB with single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition. The entire exposed collector pad is attached to the heatsink.

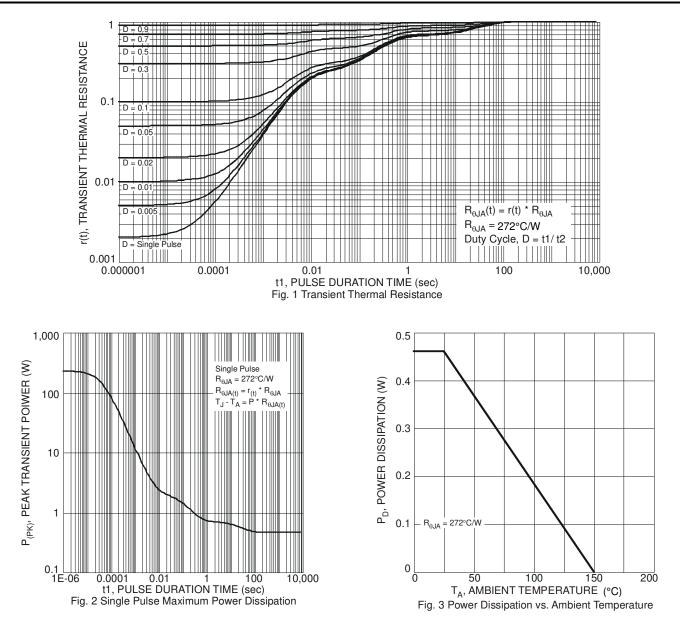
6. Same as Note 5, except device is surface mounted on 25mm X 25mm collector pad heatsink with 1oz copper.

7. Thermal resistance from junction to solder-point (at the end of the collector lead).

8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



Thermal Characteristics





Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

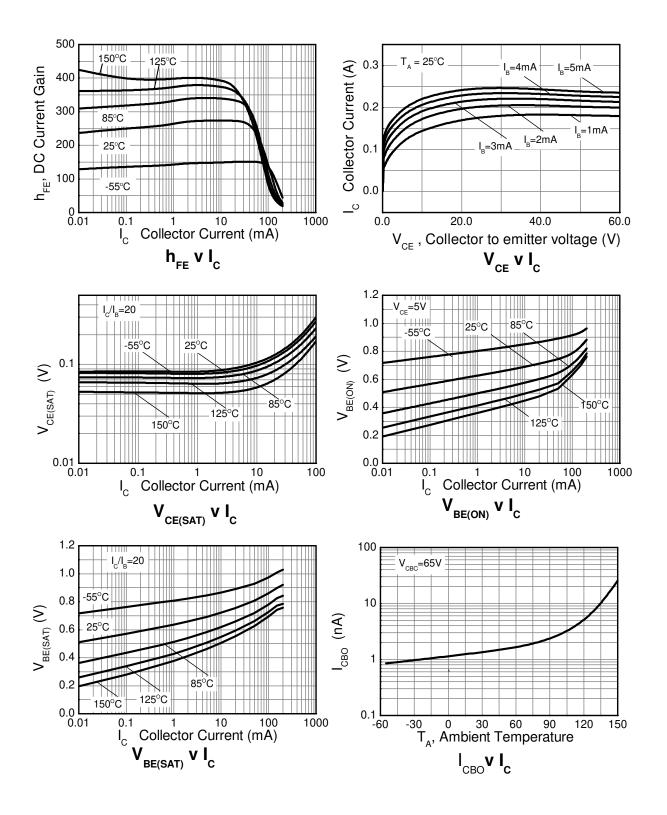
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV _{CBO}	80	_		V	$I_{\rm C} = 100 \mu A, I_{\rm E} = 0$
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	65	_	_	V	$I_{\rm C} = 10 {\rm mA}, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	6	_	_	V	$I_E = 100 \mu A, I_C = 0$
Collector Cutoff Current	ICES	_	_	15	nA	$V_{CE} = 65V$
Collector Cutoff Current	I _{CBO}	_	_	15 5.0	nA μA	V _{CB} = 40V V _{CB} = 30V, T _A = +150°C
ON CHARACTERISTICS (Note 9)	1	1		1		
DC Current Gain	h _{FE}	200	270	450	_	$V_{CE} = 5V, I_{C} = 2.0mA$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	90 220	250 600	mV	$I_{\rm C} = 10$ mA, $I_{\rm B} = 0.5$ mA $I_{\rm C} = 100$ mA, $I_{\rm B} = 5.0$ mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}		720 870	900	mV	$I_{C} = 10mA, I_{B} = 0.5mA$ $I_{C} = 100mA, I_{B} = 5.0mA$
Base-Emitter Voltage	V _{BE(ON)}	580 —	650 —	700 770	mV	$V_{CE} = 5V$, $I_C = 2.0mA$ $V_{CE} = 5V$, $I_C = 10mA$
SMALL SIGNAL CHARACTERISTICS (Note 9)	•					·
Input Capacitance	Cibo		6.7		pF	V _{CB} = 5V, f = 1.0MHz
Output Capacitance	C _{obo}		1.76		pF	$V_{CB} = 10V, f = 1.0MHz$
Current Gain-Bandwidth Product	f⊤	100	300	—	MHz	$V_{CE} = 5V, I_C = 10mA, f = 100MHz$
Noise Figure	NF	_	2	10	dB	$\label{eq:VCE} \begin{array}{l} V_{CE} = 5V, \ I_C = 200 \mu A, \ R_S = 2.0 k \Omega, \\ f = 1.0 k Hz, \ \Delta f = 200 Hz \end{array}$
Delay Time	t _D		11.2		ns	N/ 001/
Rise Time	t _R		59.7		ns	$V_{CC} = 30V,$
Storage Time	ts		190.8		ns	I _C = 150mA, I _{B1} = -I _{B2} = 15mA
Fall Time	t _F		108.6		ns	$B_1 = -B_2 = 1000A$

Note: 9. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.



BC846BLP4

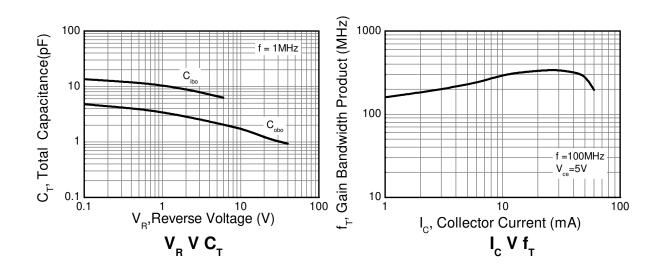
Typical Electrical Characteristics





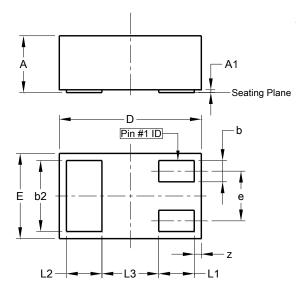
BC846BLP4

Typical Electrical Characteristics (Cont.)



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



X2-DFN1006-3				
Dim	Min	Max	Тур	
Α		0.40		
A1	0.00	0.05	0.03	
b	0.10	0.20	0.15	
b2	0.45	0.55	0.50	
D	0.95	1.05	1.00	
Е	0.55	0.65	0.60	
e	-	-	0.35	
L1	0.20	0.30	0.25	
L2	0.20	0.30	0.25	
L3	-	-	0.40	
Z	0.02	0.08	0.05	
All Dimensions in mm				

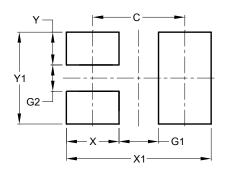
X2-DFN1006-3



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1006-3



Dimensions	Value (in mm)			
С	0.70			
G1	0.30			
G2	0.20			
Х	0.40			
X1	1.10			
Ŷ	0.25			
Y1	0.70			

IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2017, Diodes Incorporated

www.diodes.com